

Message from the CAP 2017 Organizing Committee

It is our great pleasure to welcome you to the Computer Architecture and Platforms Symposium within the the 41st IEEE International Computer Software and Applications Conference, COMPSAC 2017, organized this year in the wonderful city of Turin, Italy.

The Computer Architecture and Platforms Symposium brings together researchers and practitioners interested in developing computerized systems that consist of different components, using various metrics and methods, executed in environments containing hardware, virtual machines, software frameworks etc. These systems can have deeply embedded distributed computation in distributed infrastructures ranging in scale from micro to very large. Multidisciplinary work, research and development of software prototypes, hardware and software architectures and platforms for cyber-physical, mobile, real-time distributed systems, as well as industry-university collaborations, all based on emerging and critical technologies are of particular interest to this symposium.

Following the tradition of all COMPSAC conferences, each submission underwent a rigorous double-blind review process and was discussed by the program and organizing chairs during the PC meeting, which took place in Hong Kong, in February 2017. As the result of the process, out of 13 submissions, we accepted 16% of the submissions as regular papers and 23% of the submission as short papers for inclusion into this year's COMPSAC proceedings, published by IEEE CS. Two regular papers, 3 short papers, in addition to an invited talk will be presented across two sessions at the conference.

We thank all the authors for submitting their research results to the conference, and the members of the Program Committee and external reviewers for their dedicated, expert and careful assessment of the submissions. We thank the conference organizers including the General Chairs and Program Chairs in Chief of COMPSAC 2017.

Organizing Committee

Program Chairs

Cristina Seceleanu, Mälardalen University, Sweden
Hironori Kasahara, Waseda University, Japan

Advisory Committee Liaison

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